INTEGRATED CIRCUITS

DATA SHEET



74ALVC16244/74ALVCH16244

2.5V/3.3V 16-bit buffer/line driver (3-State)

Product specification Supersedes data of 1997 Mar 21 IC24 Data Handbook





16-bit buffer/line driver (3-State)

74ALVC16244/ 74ALVCH16244

FEATURES

- Wide supply voltage range of 1.2V to 3.6V
- Complies with JEDEC standard no. 8-1A
- CMOS low power consumption
- MULTIBYTETM flow-through standard pin-out architecture
- Low inductance multiple V_{CC} and GND pins for minimum noise and ground bounce
- Direct interface with TTL levels
- Bus hold on data inputs (74ALVCH16244 only)
- Output drive capability 50Ω transmission lines @ 85°C
- Current drive ±24 mA at 3.0 V

DESCRIPTION

The 74ALVC16244(74ALVCH16244) is a 16-bit non-inverting buffer/line driver with 3-State outputs. The device can be used as four 4-bit buffers, two 8-bit buffers or one 16-bit buffer. The 3-State outputs are controlled by the output enable inputs $1\overline{OE}$ and $2\overline{OE}$. A HIGH on $n\overline{OE}$ causes the outputs to assume a high impedance OFF-state.

The 74ALVCH16244 has active bus hold circuitry which is provided to hold unused or floating data inputs at a valid logic level. This feature eliminates the need for external pull-up or pull-down resistors.

The 74ALVC16244 has 5V tolerant inputs

PIN CONFIGURATION



QUICK REFERENCE DATA

GND = 0 V; T_{amb} = 25°C; t_{r} = t_{f} \leq 2.5 ns

SYMBOL	PARAMETER	CONDITION	IS	TYPICAL	UNIT
t _{PHL} /t _{PLH}	Propagation delay An to Yn	V _{CC} = 2.5V, CL = 30pF V _{CC} = 3.3V, CL = 50pF		1.9 1.9	ns
C _I	Input capacitance		5.0	pF	
C	Power dissipation capacitance per buffer	$V_1 = GND \text{ to } V_{CC}^1$	Outputs enabled	25	pF
C _{PD}	Power dissipation capacitance per buller	AL = QIAD to ACC.	Outputs disabled	4	рг

NOTE:

1. C_{PD} is used to determine the dynamic power dissipation (P_D in μ W): $P_D = C_{PD} \times V_{CC}^2 \times f_i + \Sigma \ (C_L \times V_{CC}^2 \times f_o) \ \text{where: } f_i = \text{input frequency in MHz; } C_L = \text{output load capacitance in pF; } f_o = \text{output frequency in MHz; } V_{CC} = \text{supply voltage in V; } \Sigma \ (C_L \times V_{CC}^2 \times f_o) = \text{sum of the outputs.}$

ORDERING INFORMATION

PACKAGES	TEMPERATURE RANGE	OUTSIDE NORTH AMERICA	NORTH AMERICA	DWG NUMBER
48-Pin Plastic SSOP Type III	-40°C to +85°C	74ALVC16244 DL	AC16244 DL	SOT370-1
48-Pin Plastic TSSOP Type II	–40°C to +85°C	74ALVC16244 DGG	AC16244 DGG	SOT362-1
48-Pin Plastic SSOP Type III	-40°C to +85°C	74ALVCH16244 DL	ACH16244 DL	SOT370-1
48-Pin Plastic TSSOP Type II	-40°C to +85°C	74ALVCH16244 DGG	ACH16244 DGG	SOT362-1

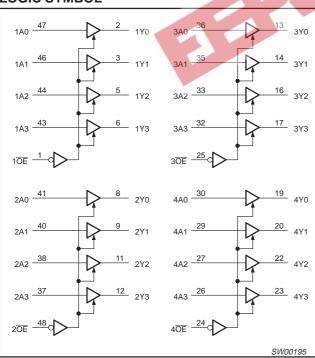
16-bit buffer/line driver (3-State)

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PIN DESCRIPTION

PIN NUMBER	SYMBOL	NAME AND FUNCTION
1	1ŌĒ	Output enable input (active LOW)
2, 3, 5, 6	1Y0 to 1Y3	Data outputs
4, 10, 15, 21, 28, 34, 39, 45	GND	Ground (0V)
7, 18, 31, 42	V _{CC}	Positive supply voltage
8, 9, 11, 12	2Y0 to 2Y3	Data outputs
13, 14, 16, 17	3Y0 to 3Y3	Data outputs
19, 20, 22, 23	4Y0 to 4Y3	Data outputs
24	4ŌE	Output enable input (active LOW)
25	3 OE	Output enable input (active LOW)
30, 29, 27, 26	4A0 to 4A3	Data inputs
36, 35, 33, 32	3A0 to 3A3	Data inputs
41, 40, 38, 37	2A0 to 2A3	Data inputs
47, 46, 44, 43	1A0 to 1A3	Data inputs
48	2 OE	Output enable input (active LOW)

LOGIC SYMBOL



FUNCTION TABLE

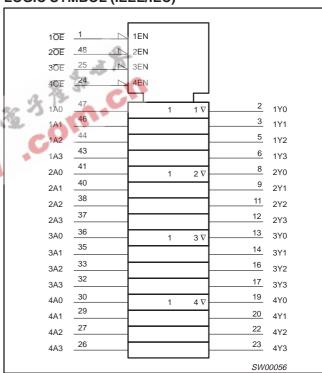
INP	UTS	OUTPUT
nOE	nAn	nYn
L	L	L
L	Н	Н
Н	Х	Z

H = HIGH voltage level L = LOW voltage level

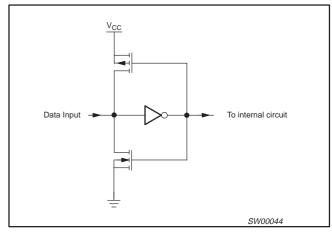
X = don't care

Z = high impedance OFF-state

LOGIC SYMBOL (IEEE/IEC)



BUS HOLD CIRCUIT



16-bit buffer/line driver (3-State)

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RECOMMENDED OPERATING CONDITIONS

OVMDOL	DADAMETER	CONDITIONS	LIN	IITS	
SYMBOL	PARAMETER	CONDITIONS	MIN	MAX	UNIT
	DC supply voltage 2.5V range (for max. speed performance @ 30 pF output load)		2.3	2.7	
V _{CC}	DC supply voltage 3.3V range (for max. speed performance @ 50 pF output load)		3.0	3.6	٧
	DC supply voltage (for low-voltage applications)		1.2	3.6	
		For data input pins with bus hold	0	V _{CC}	
V _I	DC Input voltage range	For data input pins without bus hold	0	5.5	V
		For control pins	0	5.5	
Vo	DC output voltage range		0	V _{CC}	V
T _{amb}	Operating free-air temperature range		-40	+85	°C
t _r , t _f	Input rise and fall times	V _{CC} = 2.3 to 3.0V V _{CC} = 3.0 to 3.6V	0	20 10	ns/V
In accordance	E MAXIMUM RATINGS ¹ with the Absolute Maximum Rating System (IEC 13 eferenced to GND (ground = 0V)	4) Com			

ABSOLUTE MAXIMUM RATINGS¹

SYMBOL	PARAMETER	CONDITIONS	RATING	UNIT
V _{CC}	DC supply voltage		-0.5 to +4.6	V
I _{IK}	DC input diode current	V ₁ < 0	-50	mA
		For data inputs with bus hold ²	-0.5 to V _{CC} +0.5	
V _I DC input voltage		For data inputs without bus hold ²	-0.5 to +5.5	V
		For control pins ²	-0.5 to +5.5	1
I _{OK}	DC output diode current	$V_{O} > V_{CC}$ or $V_{O} < 0$	±50	mA
Vo	DC output voltage	Note 2	-0.5 to V _{CC} +0.5	V
I _O	DC output source or sink current	$V_{O} = 0$ to V_{CC}	±50	mA
I _{GND} , I _{CC}	DC V _{CC} or GND current		± 100	mA
T _{stg}	Storage temperature range		-65 to +150	°C
P _{TOT}	Power dissipation per package -plastic medium-shrink (SSOP) -plastic thin-medium-shrink (TSSOP)	For temperature range: -40 to +125 °C above +55°C derate linearly with 11.3 mW/K above +55°C derate linearly with 8 mW/K	850 600	mW

NOTES:

^{1.} Stresses beyond those listed may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

^{2.} The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

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DC CHARACTERISTICS

Over recommended operating conditions. Voltage are referenced to GND (ground = 0 V).

				LIMITS			
SYMBOL	PARAMETER	TEST CONDITIONS	Temp	= -40°C to +	85°C	רואט [
			MIN	TYP ¹	MAX		
		V _{CC} = 1.2V	V _{CC}				
V_{IH}	HIGH level Input voltage	V _{CC} = 1.8V	0.7*V _{CC}	0.9] ,	
VIН	Thorrieverinput voltage	V _{CC} = 2.3 to 2.7V	1.7	1.2		1	
		V _{CC} = 2.7 to 3.6V	2.0	1.5		1	
		V _{CC} = 1.2V			GND		
V_{IL}	LOW level Input voltage	V _{CC} = 1.8V		0.9	0.2*V _{CC}] ,	
V IL	Low level input voltage	V _{CC} = 2.3 to 2.7V		1.2	0.7] `	
		$V_{CC} = 2.7 \text{ to } 3.6 \text{V}$		1.5	0.8		
		$V_{CC} = 1.8 \text{ to } 3.6 \text{V}; V_I = V_{IH} \text{ or } V_{IL}; I_O = -100 \mu\text{A}$	V _{CC} −0.2	V _{CC}			
		$V_{CC} = 1.8V; V_I = V_{IH} \text{ or } V_{IL}; I_O = -6\text{mA}$	V _{CC} -0.4	V _{CC} -0.10		1	
		$V_{CC} = 2.3V$; $V_I = V_{IH}$ or V_{IL} ; $I_O = -6$ mA	V _{CC} -0.3	V _{CC} -0.08		1	
V_{OH}	HIGH level output voltage	$V_{CC} = 2.3V; V_I = V_{IH} \text{ or } V_{IL}; I_O = -12\text{mA}$	V _{CC} -0.5	V _{CC} -0.17		' '	
		$V_{CC} = 2.3V; V_I = V_{IH} \text{ or } V_{IL}; I_O = -18\text{mA}$	V _{CC} -0.6	V _{CC} -0.26		1	
		$V_{CC} = 2.7V; V_I = V_{IH} \text{ or } V_{IL}; I_O = -12\text{mA}$	V _{CC} -0.5	V _{CC} -0.14		1	
		$V_{CC} = 3.0V$; $V_I = V_{IH}$ or V_{IL} ; $I_O = -24mA$	V _{CC} -1.0	V _{CC} -0.28		1	
		$V_{CC} = 1.8 \text{ to } 3.6 \text{V}; \ V_I = V_{IH} \text{ or } V_{IL}; I_O = 100 \mu\text{A}$		GND	0.20		
		$V_{CC} = 1.8V$; $V_I = V_{IH}$ or V_{IL} ; $I_O = 6mA$		0.09	0.30	1	
		$V_{CC} = 2.3V$; $V_I = V_{IH}$ or V_{IL} ; $I_O = 6mA$		0.07	0.20	1	
V_{OL}	LOW level output voltage	$V_{CC} = 2.3V$; $V_I = V_{IH}$ or V_{IL} ; $I_O = 12mA$		0.15	0.40	V	
		$V_{CC} = 2.3V$; $V_I = V_{IH}$ or V_{IL} ; $I_O = 18mA$		0.23	0.60	1	
		$V_{CC} = 2.7V; V_I = V_{IH} \text{ or } V_{IL}; I_O = 12\text{mA}$		0.14	0.40	1	
		$V_{CC} = 3.0V; V_I = V_{IH} \text{ or } V_{IL}; I_O = 24\text{mA}$		0.27	0.55	1	
	Input leakage current per data pin with bus hold	V_{CC} = 1.8 to 3.6V; $V_I = V_{CC}$ or GND		0.1	5		
II	Input leakage current per data pin without bus hold	V _{CC} = 1.8 to 3.6V; V _I = 5.5 V or GND		0.1	5	μΑ	
	Input leakage current per control pin	V _{CC} = 1.8 to 3.6V; V _I = 5.5 V or GND		0.1	5		
		$V_{CC} = 1.8 \text{ to } 2.7 \text{V}; V_{I} = V_{CC} \text{ or GND}$		0.1	10		
I _{IHZ} /I _{ILZ}	Input current for common I/O pins	$V_{CC} = 3.6V; V_1 = V_{CC} \text{ or GND}$		0.1	15	μΔ	
		V _{CC} = 1.8 to 2.7V; V _I = V _{IH} or V _{IL} ; V _O = V _{CC} or GND		0.1	5		
loz	3-State output OFF-state current	V_{CC} = 2.7 to 3.6V; V_I = V_{IH} or V_{IL} ; V_O = V_{CC} or GND		0.1	10	μ Δ	
	Outros and a second	$V_{CC} = 1.8 \text{ to } 2.7 \text{V}; V_{I} = V_{CC} \text{ or GND}; I_{O} = 0$		0.1	20	Ι,	
Icc	Quiescent supply current	$V_{CC} = 2.3 \text{ to } 3.6 \text{V}; V_{I} = V_{CC} \text{ or GND}; I_{O} = 0$		0.2	40	- μΔ	
	Additional quiescent supply current given per data I/O pin with bus hold			150	750		
Δl _{CC}	Additional quiescent supply current given per data I/O pin without bus hold	$V_{CC} = 2.7V \text{ to } 3.6V; V_1 = V_{CC} - 0.6V; I_O = 0$		5	500	μA	
	Additional quiescent supply current given per control pin			5	500		

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DC ELECTRICAL CHARACTERISTICS (Continued)

Over recommended operating conditions. Voltage are referenced to GND (ground = 0 V).

SYMBOL	PARAMETER	TEST CONDITIONS	Temp	UNIT			
			MIN	TYP ¹	MAX	1	
I _{BHL} ²	Bus hold LOW sustaining current	V _{CC} = 2.3V; V _I = 0.7V	45	-			
'BHL	BHL ² Bus floid LOVV sustaining current	V _{CC} = 3.0V; V _I = 0.8V	75	150		μΑ	
I _{BHH} ²	Bus hold HIGH sustaining current	V _{CC} = 2.3V; V _I = 1.7V	-45			μА	
I IBHH	bus floid file it sustaining current	$V_{CC} = 3.0V; V_I = 2.0V$	-75	-175			
I _{BHLO} ²	Bus hold LOW overdrive current	V _{CC} = 2.7V	300			μА	
IBHLO Bus noid EOW overdrive current		V _{CC} = 3.6V	450			μΑ	
I _{BHHO} ²	Bus hold HIGH overdrive current	V _{CC} = 2.7V	-300			μА	
івнно	bus floid File Floverative current	V _{CC} = 3.6V	-450			μΛ	

NOTES:

- 1. All typical values are at $T_{amb} = 25$ °C.
- 2. Valid for data inputs of bus hold parts.

AC CHARACTERISTICS FOR V_{CC} = 2.3V TO 2.7V RANGE AND V_{CC} < 2.3V

GND = 0V; $t_r = t_f \le 2.0$ ns; $C_L = 30$ pF

			LIMITS							
SYMBOL	PARAMETER	WAVEFORM	V _{CC} = 2.3 to 2.7V			V _{CC} = 1.8V			V _{CC} = 1.2V	UNIT
			MIN	TYP ^{1, 2}	MAX	MIN	TYP ¹	MAX	TYP ¹	
t _{PHL} /t _{PLH}	Propagation delay nAn to nYn	1,3	1.0	1.9	3.7	1.5	2.8	5.1	5.8	ns
t _{PZH} /t _{PZL}	3-State output enable time nOE to nYn	2, 3	1.0	2.5	4.9	1.5	3.8	7.1	8.4	ns
t _{PHZ} /t _{PLZ}	3-State output disable time nOE to nYn	2, 3	1.0	2.1	4.1	1.5	3.1	3.5	5.9	ns

NOTES:

- 1. All typical values are measured at $T_{amb} = 25$ °C.
- 2. Typical value is measured at $V_{CC} = 2.5V$

AC CHARACTERISTICS FOR $V_{CC} = 3.0V$ TO 3.6V RANGE AND $V_{CC} = 2.7V$

 $GND = 0V; \ t_r = t_f \le 2.5 ns; \ C_L = 50 pF$

SYMBOL	PARAMETER	WAVEFORM	Vc	$_{ extsf{C}}$ = 3.3 \pm 0	.3V	V _{CC} = 2.7V			UNIT
			MIN	TYP ^{1, 2}	MAX	MIN	TYP ¹	MAX	
t _{PHL} /t _{PLH}	PHL ^{/t} PLH Propagation delay nAn to nYn		1.0	1.9	3.0	1.0	2.1	3.6	ns
t _{PZH} /t _{PZL}	2 State output disable time		1.0	2.3	4.0	1.0	2.9	4.9	ns
t _{PHZ} /t _{PLZ}			1.0	2.7	4.1	1.0	3.0	4.5	ns

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NOTES:

- 1. All typical values are measured at $T_{amb} = 25$ °C.
- 2. Typical value is measured at $V_{CC} = 3.3V$

16-bit buffer/line driver (3-State)

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AC WAVEFORMS FOR $V_{CC} = 2.3V$ TO 2.7V AND V_{CC} < 2.3V RANGE

 $V_{M} = 0.5 V_{CC}$ $V_{X} = V_{OL} + 0.15 V_{CC}$ $V_{Y} = V_{OH} - 0.15V$

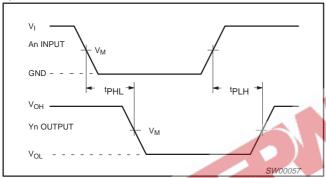
Vol. and VoH are the typical output voltage drop that occur with the output load.

 $V_I = V_{CC}$

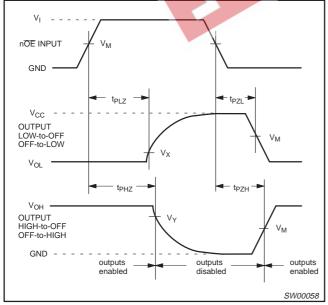
AC WAVEFORMS FOR V_{CC} = 3.0V TO 3.6V AND V_{CC} = 2.7V RANGE

 $V_{M} = 1.5 V$ $V_{X} = V_{OL} + 0.3 V$ $V_{Y} = V_{OH} - 0.3V$

V_{OL} and V_{OH} are the typical output voltage drop that occur with the output load. $V_{I} = 2.7V$

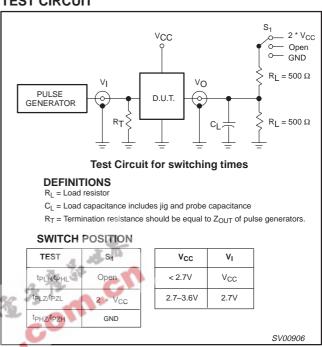


Waveform 1. Input (An) to output (Yn) propagation delay times



Waveform 2. 3-State enable and disable times

TEST CIRCUIT



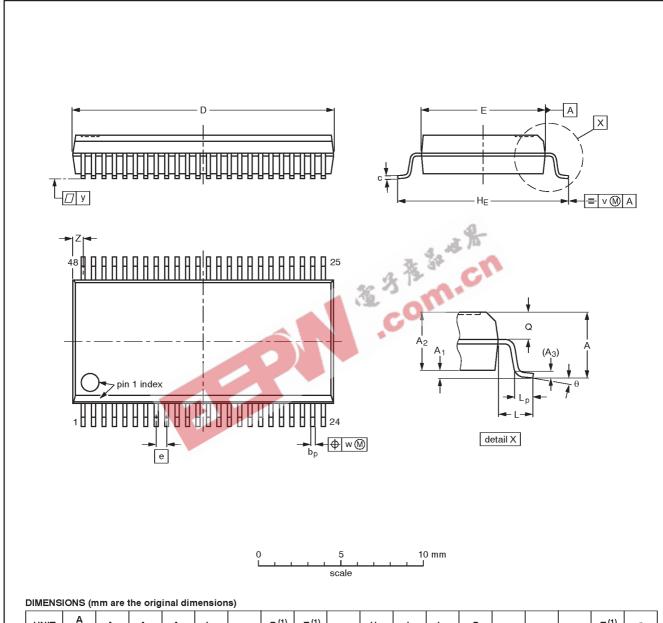
Waveform 3. Load circuitry for switching times

2.5V/3.3V 16-bit buffer/line driver (3-State)

74ALVC16244/ 74ALVCH16244

SSOP48: plastic shrink small outline package; 48 leads; body width 7.5 mm

SOT370-1



						-,												
UNIT	A max.	A ₁	A ₂	A ₃	bp	С	D ⁽¹⁾	E ⁽¹⁾	е	HE	L	Lp	Q	v	w	у	Z ⁽¹⁾	θ
mm	2.8	0.4 0.2	2.35 2.20	0.25	0.3 0.2	0.22 0.13	16.00 15.75	7.6 7.4	0.635	10.4 10.1	1.4	1.0 0.6	1.2 1.0	0.25	0.18	0.1	0.85 0.40	8° 0°

Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

	OUTLINE		REFER	EUROPEAN	ISSUE DATE		
	VERSION	IEC	JEDEC	EIAJ		PROJECTION	ISSUE DATE
	SOT370-1		MO-118AA				-93-11-02- 95-02-04

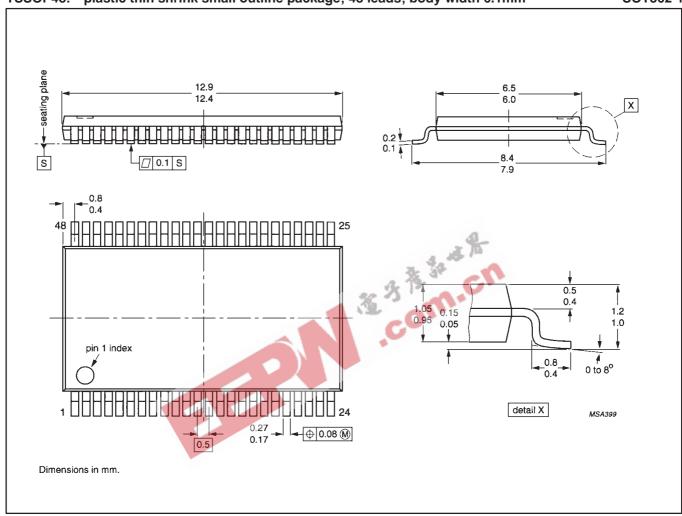
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2.5V/3.3V 16-bit buffer/line driver (3-State)

74ALVC16244/ 74ALVCH16244

TSSOP48: plastic thin shrink small outline package; 48 leads; body width 6.1mm

SOT362-1



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2.5V/3.3V 16-bit buffer/line driver (3-State)

74ALVC16244/ 74ALVCH16244

DEI INTIONO		
Data Sheet Identification	Product Status	Definition
Objective Specification	Formative or in Design	This data sheet contains the design target or goal specifications for product development. Specifications may change in any manner without notice.
Preliminary Specification	Preproduction Product	This data sheet contains preliminary data, and supplementary data will be published at a later date. Philips Semiconductors reserves the right to make changes at any time without notice in order to improve design and supply the best possible product.
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